AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A method for producing a laminated material in a web-form used for packaging containers comprised of at least a support layer and a heat-sealable inner layer, comprising:

providing a raw material roll for a support layer;

drawing out the support layer in the web-form from the raw material roll;

transferring a silver-based thin film layer vapor-deposited on a substrate on an inner face of the inside of the support layer including a zone to be heat-sealed by high frequency induction heating for the formation of the a container;

prior to or after the transferring step of the silver-based thin film layer, laminating a heat-sealable inner layer on the inside of the support layer;

printing a design of the container on the outside of the support layer in the web-form indirectly or directly; and

forming one or more thermoplastic layers of the same type or different types, at the same time or sequentially, on the outside and the inside of the printed support layer in the web-form.

2. (Original) The method for producing the packaging laminated material according to claim 1, wherein the silver-based thin film layer vapor-deposited on the substrate is transferred, on the inner face of the laminated heat-sealable inner layer,

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immediately before heat-sealing by the high frequency induction heating for the formation of the container.

- 3. (Previously Presented) The method for producing the packaging laminated material according to claim 1, wherein the silver-based thin film layer vapor-deposited on the substrate is transferred, on the inner face of a thermoplastic intermediate layer laminated on the inside of the support layer.
- 4. (Original) The method for producing the packaging laminated material according to claim 1, wherein the silver-based thin film layer vapor-deposited on the substrate is transferred, on the inner face of the inside of the support layer directly.